

Coretec Corporate Technology Matrix

Technology	2008	2009	2010 - 2012
Laminates; Drivers: Frequency creep, Signal integrity, Reduced parasitic			
Dk range	2.2 - 10	2.2 - 10	2.2 - 10
Low Dk/Low Df	3.8/.010	3.5/.002	3.0/.002
Pb Free			
Thermally Conductive (>0.9 W/Mk) Multilayer			
Halogen Free			
Imaging Minimum Line/Space (Internal)			
.005/.005 1 oz			
.004/.004 1 oz			
.003/.003 1/2 oz			
.002/.002 1/4 oz			
Imaging Minimum Line/Space (External / Plated Internal)			
.005/.005 1 oz			
.004/.004 1/2 oz			
.003/.003 1/2 oz			
.002/.002 1/4 oz			
Pad Size (assuming Tangency)			
Pad = Drill + .010			
Pad = Drill + .008			
Pad = Drill + .006			
Anti-pad minimum feature			
Anti-pad = Drill + .018			
Anti-pad = Drill + .016 (assuming CAF resistant laminate)			
Anti-pad = Drill + .015 (assuming CAF resistant laminate)			
Drill size (minimum)			
0.010 (.0098)			
0.008 (.0078)			
0.006 (.0059)			
0.004			
Via and PTH technology			
Aspect ratio 7:1			
Aspect ratio 10:1			
Aspect ratio 12:1			
Aspect ratio 15:1			
Micro Vias			
Drill + .006 (Pad Tangency)			
Drill + .004 (Pad Tangency)			
Aspect Ratio 0.75:1			
Aspect Ratio 1:1			
Aspect Ratio 1.2:1			
Plugged/Plated shut μ vias			
Stacked μ vias			
Sequential Lamination			
2 Lamination Cycles			
3 Lamination Cycles			
4+ lamination Cycles			
Embedded Passives			
Capacitors			
Planar (.002")			
Planar (<.001")			
Discrete (Ceramic)			
Discrete (Polymer Thick Film)			
Resistors			
Discrete R/C placed via cavity			
NIP Supplied Laminate			
Thick Film Ceramic			
Thick Film Polymer			
Trimming of R/C (sub-contract)			
Solder Mask			
Feature Resolution 3 mils			
Feature Registration. +/- 1 mil			
Surface Finishes			
HASL			
ENIG			
Electrolytic Au (Hard)			
Electrolytic Au (Soft)			
Immersion Ag			
Immersion Sn			
PbSn Reflow			
OSP			
Ni Pl Au			
Other			
Active cavity PWBs			
PCI Buss connector on 16 layer+			
Optical Drill			
Control Depth drill (+/- .0002")			
Metal Core			
Impedance Control +/- 10%			
Impedance Control +/- 5%			
Plasma etchback			
Conductive/Non-conductive via plug			
Heatsink (external and buried)			
Rigid-Flex			
Flex			
Opto Electronics			

	Standard Volume Technology
	Limited Volume Technology
	Development Technology
	Not capable or No Plans to Develop